

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

EPAS ID: PAT7366882

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
SIDDARTH SUNDARESAN	06/02/2021
RANBIR SINGH	06/02/2021
JAEHOON PARK	06/02/2021
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	GENESIC SEMICONDUCTOR INC.
<b>Street Address:</b>	43670 TRADE CENTER PLACE, STE. 155
<b>City:</b>	DULLES
<b>State/Country:</b>	VIRGINIA
<b>Postal Code:</b>	20166
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	17677068
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	2407152061
<b>Email:</b>	support@davelawgroup.com
<b>Correspondent Name:</b>	DAVÉ LAW GROUP, LLC
<b>Address Line 1:</b>	2000 DUKE STREET, SUITE 300
<b>Address Line 4:</b>	ALEXANDRIA, VIRGINIA 22314
<b>ATTORNEY DOCKET NUMBER:</b>	GSIC-010-01US
<b>NAME OF SUBMITTER:</b>	RAJ S. DAVÉ
<b>SIGNATURE:</b>	/ Raj S. Davé /
<b>DATE SIGNED:</b>	06/06/2022
<b>Total Attachments: 7</b>	
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Attorney Docket No. GSIC-010-00US

### ASSIGNMENT

Siddarth Sundaresan, Ranbir Singh and Jaehoon Park, having a mailing address of c/o GeneSiC Semiconductor Inc., 43670 Trade Center Place, Ste. 155, Dulles, VA 20166 (US) (referred to as "Assignor") has made an invention(s) (the "Invention(s)") set forth in an application for patent entitled **METHOD AND MANUFACTURE OF ROBUST, HIGH-PERFORMANCE DEVICES**, and which is a:

- (1)  provisional application
  - (a)  to be filed herewith; or
  - (b)  bearing Application No. , and filed on;
- (2)  non-provisional application
  - (a)  to be filed herewith; or
  - (b)  bearing Application No. 17/334,935; and filed on May 31, 2021  
and/or
- (3)  PCT application
  - (a)  bearing Application No., and filed on;  
  
and/or
- (4)  attached hereto.

GeneSiC Semiconductor Inc., having its principal place of business at 43670 Trade Center Place, Ste. 155, Dulles, VA 20166 (US), its successors, legal representatives and assigns, (the "Assignee"), is desirous of acquiring the entire right, title, and interest in: the Invention(s); the application(s) for patent identified above; the right to file applications for patent of the United States or other countries on the Invention(s); any application(s) for patent of the United States or other countries claiming priority to, and/or the benefit of, these applications; any provisional or other right to recover any and all past, present, and future damages, including royalties, for any and all past, present, and future infringements of these application(s); and any and all patent(s) of the United States or other countries that may be granted therefor or thereon.

**NOW, THEREFORE**, for good and sufficient consideration, the receipt of which is hereby acknowledged, and to the extent that the Assignor has not done so already via a prior agreement with the Assignee or a predecessor in interest of the Assignee, or if the Assignor has already done so via a prior agreement with the Assignee or a predecessor in interest of the Assignee then in confirmation of any obligation to do so in said prior agreement, the Assignor has sold, assigned, transferred, and set over, and by these presents does sell, assign, transfer, and

set over, unto the Assignee, its successors, legal representatives, and assigns, the Assignor's entire right, title, and interest in:

(a) the Invention(s);

(b) the application(s) for patent identified above;

(c) the right to file applications for patent of the United States or other countries on the Invention(s), including all rights under the Hague Convention, the Paris Convention for the Protection of Industrial Property, and under the Patent Cooperation Treaty, and all rights of claiming priority in any country of the world;

(d) any application(s) for patent of the United States or other countries claiming the Invention(s);

(e) any application(s) for patent of the United States or other countries claiming priority to, and/or the benefit of, at least one of the application(s) for patent identified above or any application(s) for patent claiming the Invention(s), including any priority application(s), substitute application(s), division(s), continuation(s), and continuation(s)-in-part;

(f) any provisional or other right to recover any and all past, present, and future damages, including royalties, for any and all past, present, and future infringements of any application for patent identified in the preceding paragraphs (b)-(e) and of any and all patent(s) granted based thereon in the United States and in all other countries; and

(g) any patent(s) of the United States or other countries that may be granted for or on any application for patent identified in the preceding paragraphs (b)-(e), including any reissue(s), reexamination(s), revival(s), renewal(s) and extension(s) of said patent(s).

The above-granted rights, titles, and interests are to be held and enjoyed by the Assignee, for its own use and behalf and the use and behalf of its successors, legal representatives, and assigns, as fully and entirely as the same would have been held and enjoyed by the Assignor had this sale and assignment not been made.

The Assignor hereby represents to the Assignee, its successors, legal representatives, and assigns, that, at the time of execution and delivery of these presents, or if applicable, at such time said prior agreement was executed, the Assignor is a lawful owner of an undivided interest in the entire right, title, and interest in and to the Invention(s), that the Invention(s) are unencumbered, except, if applicable, by obligation to assign in accordance with said prior agreement, and that the Assignor has good and full right and lawful authority to sell and convey the same in the manner set forth herein, and that Assignor will not make or enter into any assignment, sale, agreement or encumbrance which would conflict with these presents.

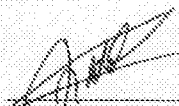
The Assignor hereby covenants and agrees to and with the Assignee, its successors, legal representatives, and assigns, that the Assignor will sign all papers and documents, take all lawful

oaths, and do all acts necessary or required to be done in connection with any and all proceedings for the procurement, maintenance, enforcement and defense of the Invention(s), said application(s), and said patent(s), including interference and derivation proceedings, and any post-grant proceedings (e.g., opposition proceedings, post-grant reviews, *Inter partes* reviews, supplemental examinations, etc.) without charge to the Assignee, its successors, legal representatives, and assigns, but at the cost and expense of the Assignee, its successors, legal representatives, and assigns.

The Assignor hereby authorizes and requests the attorneys of Dave Law Group to insert in the spaces provided above the filing date, the application number, and the attorney docket number of the application(s) identified above when known.

The Assignor hereby requests the Commissioner of Patents to issue said patents of the United States to the Assignee for the sole use and behalf of the Assignee, its successors, legal representatives, and assigns.

Date: 06/02/21

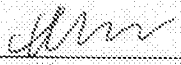
By:   
Siddarth Sundaresan

I certify that I know or have satisfactory evidence that **Siddarth Sundaresan** signed this instrument of his/her own free will, as a voluntary act for the uses and purposes mentioned in the instrument.


Date 06/02/2021  
(Type or Print)

Signed at Dulles, VA

Yu Dong  
(Type or Print Name of Witness)

  
(Signature of Witness)


Date: 06/02/21

By:   
Ranbir Singh

I certify that I know or have satisfactory evidence that **Ranbir Singh** signed this instrument of his/her own free will, as a voluntary act for the uses and purposes mentioned in the instrument.

Date 06/02/2021 Signed at Dulles, VA  
(Type or Print)

Yu Dong  
(Type or Print Name of Witness)

  
(Signature of Witness)

Date: June 2, 2021

By:

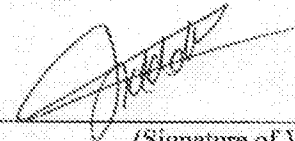
  
Jaehoon Park

I certify that I know or have satisfactory evidence that Jaehoon Park signed this instrument of his/her own free will, as a voluntary act for the uses and purposes mentioned in the instrument.

Date 06/02/21  
(Type or Print)

Signed at DULLES, VA

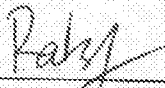
SID SUNDARESAN  
(Type or Print Name of Witness)

  
(Signature of Witness)



For and on behalf of ASSIGNEE:

Date: 06/02/21

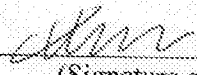
By:   
Signatory Name: RANBIR SINGH  
Signatory Title: PRESIDENT  
Applicant Name: GenSiC Semiconductor Inc.

I certify that I know or have satisfactory evidence that RANBIR SINGH signed this instrument of his/her own free will, as a voluntary act for the uses and purposes mentioned in the instrument.

Date 06/07/2021  
(Type or Print)

Signed at Dallas, VA

Vu Pong  
(Type or Print Name of Witness)

  
(Signature of Witness)